



Tool Make & Model

Tool Configuration / Specifications

Pos.	Mark	Code	Description	Quantity
Base Systems				
1		A4HD	FINEPLACER® pico; base system, with manual zoom camera Z12 and USB 1.3 Mpix, and LED illumination Pico 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
Pivot Arms				
2		AP2.4L	Placement Arm long with theta fine rotation, for all A4V models AP2.4L 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
Adjustment Sets				
3		AJ1.P	Adjustment Set, resolution 5 µm, for placement accuracy verification, for Placement Arm, for all A2V, A3V and A4V models 5µm resolution	1.00
Accessories for Base Systems				
4		...SH	Optics shifting up to 85 mm, with fixture for second working position, for A2V, A2V.H, A2V.RV10, A4V, A4V.H and A4V.RV10 X1200000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
5		...YS	In addition to the video module, enables horizontal movement of the camera up to +/- 10 mm (Y), surcharge Y 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
6		AC1	Target Finder for all A2V, A3V and A4V models AC1 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
7		AC3LED	Coaxial illumination (LED) for all A2V, A3V and A4 models for head and / or target AC3LED 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	2.00
8		FT1	Height adjustable tracks for positioning table, surcharge to base module (for A2 and A4) FT1 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
Heating Plates				
9		FA9CV	Heating Plate 100 mm x 100 mm, 1200 W, with vacuum holder, PC controlled with FS4, for all A2V and A4V models FA9CV 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
Process Gas Systems for Heating Plates				
10		...IF	Inert Gas Enclosure, manual version, standard shape, gas flow adjustment via knob, flow reading via float-type flow meter IF 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
Tools, heated / unheated				

11		APH2.S	Placement Head for Placement Arm, customer specified, standard unheated, for DFB LD for example APH2.S 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	2.00
Bonding Force Modules				
12		FD3.1	Bonding Force Module, manual, force range 0.1 N - 20 N, resolution 0.1 N, for all A2V, A4V and A6V models FD3.1 600000x1.3 Mpix, 600000x1.3 Mpix, 600000x1.3 Mpix	1.00
PC and Software				
13		PC	PC with monitor, complete (for FS4, RA8), Software installed and configured	1.00
14		FS4	Bonding software Win Flip Chip for PC controlled modules	1.00
15		FS4.M	WinFlipChip Software Mask Generator, surcharge to FS4	1.00
Video Modules and optical accessory				
16		RW3.XLED	Observation and inspection video module with variable angle (without monitor) with LED light	1.00

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